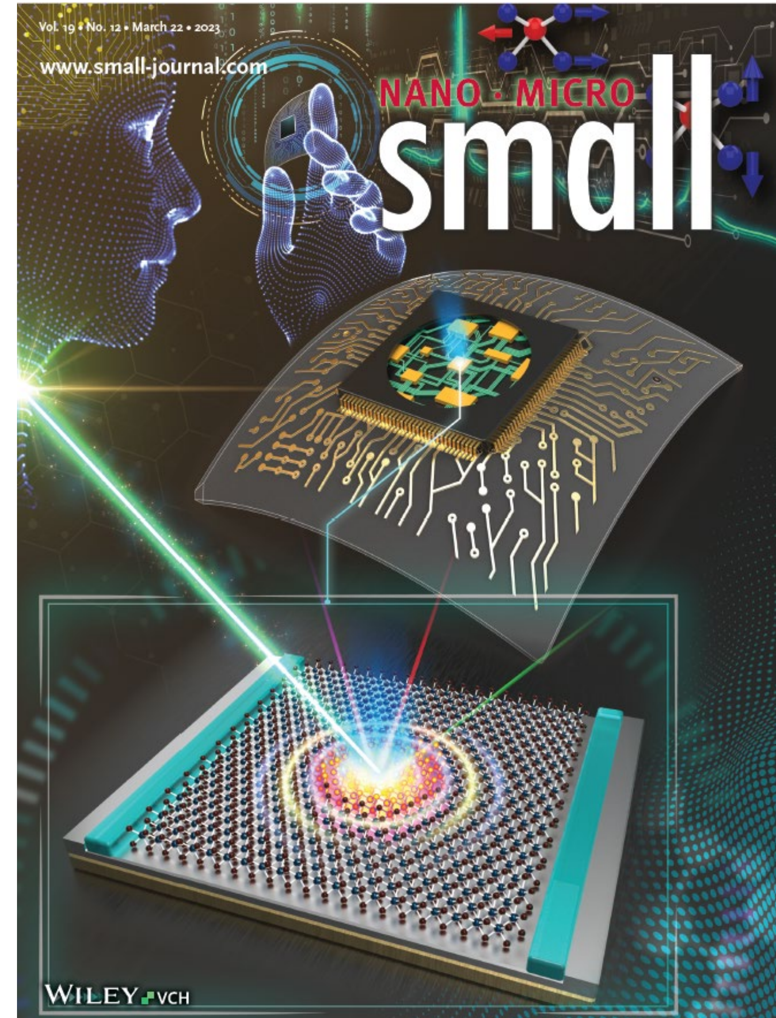
Ultra-High Interfacial Thermal Conductance via Double hBN Encapsulation for Efficient Thermal Management of 2D Electronics

Xian Zhang, Stevens Institute of Technology

- This study reports the hBN encapsulation structure as an ultra-high heat dissipation.
- This finding helps to address the challenge for the inefficient thermal management in flexible electronics.
- It also opens a new route for the exploration of future electronics by leveraging the unique thermal properties of 2D materials and structures.



Mentoring girls today can help accelerate the closing of the gender gap in engineering tomorrow

Xian Zhang, Stevens Institute of Technology

- Co-organized the "Introduce a Girl to Engineering Day" as part of National Engineers Week.

- The event offered a chance for under-represented groups with limited exposure to STEM to learn what engineering is all about and inspire a future in it!